PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shinichi Akiyama	02/01/2011
Hiroaki Yoshino	02/01/2011
Shinsuke Tei	02/01/2011

RECEIVING PARTY DATA

Name:	Shinkawa Ltd.
Street Address:	51-1, Inadaira 2-chome, Musashimurayama-shi
City:	Tokyo
State/Country:	JAPAN
Postal Code:	208-8585

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13014109

CH $40.00 13014109

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Pedro C. Fernandez

Total Attachments: 2
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ASSIGNMENT

Docker No. SHIN 24.619

WHEREAS, the below named inventor, ASSIGNOR, has made a certain new and useful invention in: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND WIRE BONDING APPARATUS

for which
(check one) [ ] an application is being filed concurrently herewith,

[X] an application for a Patent of the United States was filed on January 26, 2011
and given Application Serial No. 13/014,109

and WHEREAS, Shinkawa Ltd.
having a place of business at 51-1, Inadaira 2-chome, Musashimurayama-shi
Tokyo, Japan 208-8585 ASSIGNEE
is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar ($1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument; and

ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed, and will not execute, any agreement in conflict herewith; and

ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

Full name of sole or first inventor Shinichi Akiyama
Inventor's Signature Date Feb 1, 2011
Residence Tokyo, Japan Citizenship Japanese
Post Office Address c/o Shinkawa Ltd.
51-1, Inadaira 2-chome, Musashimurayama-shi, Tokyo, Japan 208-8585

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Docket No. SHIN 24.619

Full name of second joint inventor, if any Hiroaki Yoshino
Second Inventor's Signature 吉野 浩章 Date Feb. 1, 2011
Residence Tokyo, Japan Citizenship Japanese
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Full name of third joint inventor, if any Shinsuke Tei
Third Inventor's Signature Date Feb. 1. 2011
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Full name of fourth joint inventor, if any
Fourth Inventor's Signature Date
Residence Citizenship
Post Office Address

Full name of fifth joint inventor, if any
Fifth Inventor's Signature Date
Residence Citizenship
Post Office Address

Full name of sixth joint inventor, if any
Sixth Inventor's Signature Date
Residence Citizenship
Post Office Address